

00-689/1D

**IN THE SPECIFICATION**

Please amend the first paragraph on page 2 of the application as given below:

This is a divisional of copending application serial number 10/007,247 filed  
2001.11.01, now United States patent 6,678,950. This invention relates to the field of  
integrated circuit manufacturing. More particularly, the invention relates to the design  
5 and manufacture of bonding pads for an integrated circuit.